

ABSTRACT

The present disclosure provides an auxiliary temperature-control device for a semiconductor process chamber and a semiconductor process chamber. The auxiliary
5 temperature-control device includes a heat conduction assembly, which is configured to be fixedly connected to the semiconductor process chamber for heat exchange with a process kit in the semiconductor process chamber; a cooling channel, which is disposed in the heat conduction assembly, and is configured to introduce a cooling fluid to cool the heat conduction assembly; and a heating assembly, which is disposed in the heat
10 conduction assembly, and is configured to heat the heat conduction assembly. In the auxiliary temperature-control device provided herein, by providing the heat conduction assembly and disposing the cooling channel and the heating assembly in the heat conduction assembly, a temperature of the heat conduction assembly can be adjusted with the cooling channel and the heating assembly, and heat exchange can be performed
15 between the heat conduction assembly and the process kit to adjust a temperature of the process kit, so that the temperature of the process kit can be prevented from being too high or too low to affect wafers, which can improve wafer product quality.